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flexible and (semiconductive or semiconductor) and organic and polymer

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 Print Format**Results:**Journal or Magazine = **JNL** Conference = **CNF** Standard = **STD****1 A flexible conjugated polymer laser using 2D distributed feedback**

Riechel, S.; Kallinger, C.; Lemmer, U.; Feldmann, J.; Gombert, A.;

Wittwer, V.; Scherf, U.;

Lasers and Electro-Optics, 1999. CLEO '99. Summaries of Papers

Presented at the Conference on , 23-28 May 1999

Page(s): 465 -466

[\[Abstract\]](#) [\[PDF Full-Text \(224 KB\)\]](#) **IEEE CNF****2 Roll-up displays: fact or fiction?**

Collins, L.;

IEE Review , Volume: 49 Issue: 2 , Feb. 2003

Page(s): 42 -45

[\[Abstract\]](#) [\[PDF Full-Text \(340 KB\)\]](#) **IEE JNL****3 An organic thin film transistor backplane for flexible liquid crystal displays**

Sheraw, C.D.; Nichols, J.A.; Gundlach, D.J.; Huang, J.R.; Kuo, C.C.;

Klauk, H.; Jackson, T.N.; Kane, M.G.; Campi, J.; Cuomo, F.P.;

Greening, B.K.;

Device Research Conference, 2000. Conference Digest. 58th DRC ,

19-21 June 2000

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[\[Abstract\]](#) [\[PDF Full-Text \(180 KB\)\]](#) **IEEE CNF**

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security AND (strip OR thread) AND (IC OR chip OR (integrated AND circuit))

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Print Format

1 Crafting a Java virtual machine in silicon*Hardin, D.S.*IEEE Instrumentation & Measurement Magazine , Volume: 4 Issue: 1 ,
March 2001

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[\[Abstract\]](#) [\[PDF Full-Text \(460 KB\)\]](#) **JNL****2 Smart-cards-a cost-effective solution against electronic fraud***Lassus, M.*Security and Detection, 1997. ECOS 97., European Conference on ,
1997

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[\[Abstract\]](#) [\[PDF Full-Text \(340 KB\)\]](#) **CNF****3 Paper based document security-a review***van Renesse, R.L.*Security and Detection, 1997. ECOS 97., European Conference on ,
1997

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[\[Abstract\]](#) [\[PDF Full-Text \(508 KB\)\]](#) **CNF****4 Crypt graphic smart cards***Naccache, D.; M'Raihi, D.*

IEEE Micro , Volume: 16 Issue: 3 , June 1996

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(semiconductive AND organic AND polymer)

Results:Journal or Magazine = **JNL** Conference = **CNF** Standard = **STD****76 Migration of vinyl acetate from semiconductive to insulation of power cables***Haridoss, S.*

Electrical Insulation, 1990., Conference Record of the 1990 IEEE International Symposium on , 1990

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[\[Abstract\]](#) [\[PDF Full-Text \(328 KB\)\]](#) **CNF****77 A new concept for medium-voltage cables: improved voltage life of belt-type cables***Kreuger, F.H.; Morshuis, P.H.F.; van de Laar, A.M.F.*

Electrical Insulation, IEEE Transactions on [see also Dielectrics and Electrical Insulation, IEEE Transactions on] , Volume: 24 Issue: 6 , Dec. 1989

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[\[Abstract\]](#) [\[PDF Full-Text \(468 KB\)\]](#) **JNL****78 Dielectric breakdown strength affected by the lamellar configuration in XLPE insulation at a semiconducting interface***Okamoto, T.; Ishida, M.; Hozumi, N.*

Electrical Insulation, IEEE Transactions on [see also Dielectrics and Electrical Insulation, IEEE Transactions on] , Volume: 24 Issue: 4 , Aug. 1989

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[\[Abstract\]](#) [\[PDF Full-Text \(644 KB\)\]](#) **JNL**

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Schrodner, M.; Sensfuss, S.; Roth, H.-K.; Stohn, R.-I.; Clemens, W.; Bernds, A.; Fix, W.

Polymers and Adhesives in Microelectronics and Photonics, 2001. First International IEEE Conference on , 2001

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[\[Abstract\]](#) [\[PDF Full-Text \(393 KB\)\]](#) **CNF****2 Will polymer electronics change the electronics industry?***Hofstraat, H.*

Polymers and Adhesives in Microelectronics and Photonics, 2001. First International IEEE Conference on , 2001

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[\[Abstract\]](#) [\[PDF Full-Text \(713 KB\)\]](#) **CNF****3 Manufacturability and reliability of non-halogenated molding compounds**

Cada, L.G.; Lalanto, R.; Coronel, G.; San Gregorio, N.; Asis, D.; Ong, G.; Ducusin, C.; Desengano, R.; Llamas, T.; Decena, R.; Canares, N.; Reyes, A.; Miciano, P.

Electronics Packaging Technology Conference, 2000. (EPTC 2000). Proceedings of 3rd , 2000

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[\[Abstract\]](#) [\[PDF Full-Text \(324 KB\)\]](#) **CNF****4 Polymer electronics and semiconductor grafting for aerospace applications**

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Schrodner, M.; Sensfuss, S.; Roth, H.-K.; Stohn, R.-I.; Clemens, W.; Bernds, A.; Fix, W.

Polymers and Adhesives in Microelectronics and Photonics, 2001. First International IEEE Conference on , 2001

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2	BRS L2	(Kruel-J.in · Hart-C.in · DeLeeuw-D.in · DeHesse-W.in · Matters-M.in.) and @pd>20030715	USPAT; US-PGPUB ; EPO; JPO	2003/07/27 18:01	0	
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4	BRS L4	((paper cardboard) near5 (IC (integrated adj circuit chip)) same (organic polymer) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:02	0	
5	BRS L5	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same ((security near2 (strip thread)) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:02	0	
6	BRS L6		USPAT; US-PGPUB	2003/07/27 18:03	0	

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		((paper cardboard currency passport) near5 (ic chip semiconductor\$3) and (security near2 (strip thread)) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:04			0
7	BRS L7 0	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (organic near2 polymer) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:04	*		0
8	BRS L8 0	conduct\$3 near5 (security near2 (strip thread)) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:04			0
9	BRS L9 0	(conduct\$3 near5 (security near2 (strip thread)) and (hologram optical\$2 foil kinigram) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:04			0
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15	BRS L15 0	(organic near2 polymer) same polyimide same polyaniline and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:07
16	BRS L16 0	(ic circuit semiconductor same polyimide adj10 polyaniline) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:07
17	BRS L17 1	polyimide adj10 polyaniline and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:07
18	BRS L18 0	(security near2 (strip thread)) same (size thickness width thick) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:08
19	BRS L19 5	(banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1))) same (IC chip circuit semiconductor semiconducting) and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:08

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22	BRS L22 1	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) near5 polymer\$2 and @pd>20030715	USPAT; US-PGPUB	2003/07/27 18:12	0		
23	BRS L23 0						

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24	BRS L24 0	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20030715	EPO; JPO; DERWENT; IBM_TDB	2003/07/27 18:12			0
25	BRS L25 0	"6547151" . PN.	USPAT; US_PGPUB	2003/07/27 18:50			0
26	I S& R	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor) near5 paper	USPAT; US_PGPUB	2003/07/27 19:29			0
27	BRS L56 9	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor) near5 organic	USPAT; US_PGPUB	2003/07/27 19:29			0
28	BRS L57 53	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor) near5 organic	USPAT; US_PGPUB	2003/07/27 19:20			0
29	BRS L58 33	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor) near5 organic	EPO; JPO; DERWENT; IBM_TDB	2003/07/27 19:20			0
30	BRS L59 5	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor) near5 paper	EPO; JPO; DERWENT; IBM_TDB	2003/07/27 19:29			0

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32	BRS L67 819			
33	BRS L68 522			
34	BRS L69 623			

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39	BRS	L74 10	paper near5 (ic chip semiconductor) near5 (antenna coil)	USPAT; US-PGPUB	2003/07/27 21:43			0
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105	BRS 0		USPAT; US-PGPUB	2003/07/15 08:22	0	0	

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108	BRS 0	conduct\$3 near5 (security near2 (strip thread)) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:23			0
109	BRS 0	(conduct\$3 near5 (security near2 (strip thread)) and (hologram optical\$2 foil kinigram) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:24			0
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				da t a s	Error	Defin it ion
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Type	Hits	Search Text	DBs	Time Stamp	C o m m e n t	E r r o r	Definition
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		((banknotes\$1 (bank adj notes\$1) passport (security adj1 (document\$1 paper\$1 threads\$1 strip\$1)) same (IC chip circuit semiconductor semiconducting) not ((banknotes\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1)) same (IC chip circuit semiconductor semiconducting)) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 09:49			0
119	3	(banknotes\$1 (bank adj notes\$1) passport (security adj1 (document\$1 paper\$1 threads\$1 strip\$1)) same (IC chip circuit semiconductor semiconducting) and @pd>20021031	EPO; JPO; DERWENT; IBM_TDB	2003/07/15 10:06			0
120	32	(flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) (flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) (flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2	USPAT; US-PGPUB	2003/07/15 10:09			0
121	9506	(flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) (flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) (flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2	USPAT; US-PGPUB	2003/07/15 12:46			0
122	134	(flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) (flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) (flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2	USPAT; US-PGPUB	2003/07/15 12:40			0
123	7	(flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) (flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2	USPAT; US-PGPUB	2003/07/15 12:40			0

Type	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r s	Error Definition
124	BRS 5	(flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2	EPO; JPO; DERWENT; IBM_TDB	2003/07/15 12:40	0	0	
125	BRS 71	(flexible flexibility bends\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer)	EPO; JPO; DERWENT; IBM_TDB	2003/07/15 12:47	0	0	